

Annex to declaration of accreditation (scope of accreditation)
 Normative document: ISO/IEC 17025:2005
 Registration number: **L 388**

of **MASER Engineering B.V.**
Enschede

This annex is valid from: **28-09-2017** to **01-10-2021**

Replaces annex dated: **07-07-2015**

Location where activities are performed under accreditation

Head Office

Capitool 56
 7521 PL Enschede
 Nederland

No.	Material or product	Type of activity	Internal reference number
1.	Electronic components	Exposure of (non) heat-dissipating electronic components to calibrated and controlled temperature, humidity and bias conditions	RF_JESD22-A101 conform JESD22-A101 RF_JESD22-A110 conform JESD22-A110
2.		Exposure of electronic components to calibrated and controlled temperature and humidity conditions	RF_JESD22-A102 conform JESD22-A102 RF_JESD22-A118 conform JESD22-A118 RF_IEC 60068-2-78 conform IEC 60068-2-78
3.		Exposure of electronic components to calibrated and controlled high temperature conditions	RF_JESD22-A103 conform JESD22-A103 RF_IEC 60068-2-2 conform IEC 60068-2-2 RF_MIL-STD-883 m1008 conform MIL-STD-883 method 1008
4.		Exposure of electronic components to calibrated and controlled alternating temperature conditions	RF_JESD22-A104 conform JESD22-A104 RF_IEC 60068-2-14 conform IEC 60068-2-14 RF_MIL-STD-883 m1010 conform MIL-STD-883 method 1010
5.		Exposure of heat-dissipating electronic components to calibrated and controlled alternating bias and alternating temperature conditions	RF_JESD22-A105 conform JESD22-A105

This annex has been approved by the Board of the Dutch Accreditation Council, on its behalf,

J.A.W.M. de Haas
 Director of Operations

of **MASER Engineering B.V.**
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No.	Material or product	Type of activity	Internal reference number
6.	Electronic components	Exposure of (non) heat-dissipating electronic components to calibrated and controlled temperature and bias conditions	RF_JESD22-A108 conform JESD22-A108 RF_AEC Q100-008 conform AEC Q100-008
7.		Exposure of electronic components to calibrated and controlled low temperature conditions	RF_JESD22-A119 conform JESD22-A119 RF_IEC 60068-2-1 conform IEC 60068-2-1
8.		Exposure of electronic components to calibrated and controlled alternating temperature and alternating humidity conditions	RF_IEC 60068-2-30 conform IEC 60068-2-30
9.		Exposure of electronic components to calibrated and controlled alternating humidity, alternating temperature and bias conditions	RF_JESD22-A100 conform JESD22-A100 RF_IEC 60068-2-38 conform IEC 60068-2-38 RF_MIL-STD-883 m1004 conform MIL-STD-883 method 1004
10.		Exposure of bond wires of electronic components to calibrated and controlled pull forces	RF_MIL-STD-883 m2011 conform MIL-STD-883 method 2011
11.		Exposure of bond wires, dies or solderballs of electronic components to calibrated and controlled shear forces	RF_MIL-STD-883 m2019 conform MIL-STD-883 method 2019 RF_AEC Q100-001 conform AEC Q100-001 RF_AEC Q100-010 conform AEC Q100-010 RF_JESD22-B116 conform JESD22-B116 RF_JESD22-B117 conform JESD22-B117